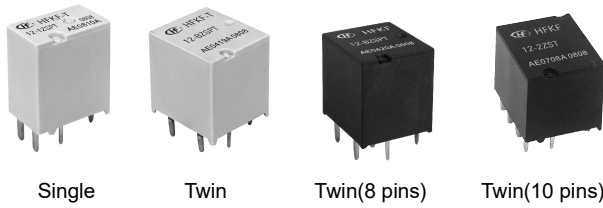


HFKF/HFKF-T

AUTOMOTIVE RELAY



Typical Applications

Central door lock, Power doors and windows, Seat adjustment, Sunroof motor control, Mirror adjustment

Features

- 25A motor locked load
- Extremely small relay
- Change-over contact version
- Single and twin(8 pins or 10 pins) version available
- Coil wire insulation class H (180°C)
- HFKF-T (reflow soldering version) available
- RoHS & ELV compliant

CHARACTERISTICS

Contact arrangement	1C (Single), 2C Twin(8 pins), 2C Twin(10 pins)		Shock resistance	Functional ⁸⁾	100m/s ² (pulse duration: 11ms)
Voltage drop (initial) ¹⁾	Typ.: 50mV (at 10A)		Termination	Destructive	1000m/s ² (pulse duration: 6ms)
	Max.: 250mV (at 10A)			PCB ⁹⁾	
Max. continuous current ²⁾	35A 2min 12VDC at 23°C		Construction	Plastic sealed, Flux proofed	
	HFKF:25A 2min 12VDC at 85°C			Single relay: Approx. 3.5g	
	HFKF-T:30A 2min 12VDC at 85°C			Twin relay: Approx. 6.5g	
	HFKF-T:20A 2min 12VDC at 125°C				
Max. switching current ³⁾	NO:60A NC:30A		Unit weight		
Max. switching voltage	16VDC		1) Equivalent to the Typ. initial contact resistance is 5mΩ (at 10A). Equivalent to the max. initial contact resistance is 100mΩ (at 1A 6VDC).		
Min. contact load ⁴⁾	1A 12VDC		2) Test under the following conditions:		
Electrical endurance	See "CONTACT DATA"		a. The relay is mounted on the PCB, the coil is applied with 100% rated voltage.		
Mechanical endurance	1 x 10 ⁷ OPS (300OPS/min)		b. The PCB board is a double layer board. the thickness of the copper foil is 4oz(140μm), the width of each copper foil is 3.76x(1±5%)mm, the length of copper foil is 50mm±1mm and the Tg value of the PCB board is 150°C.		
Initial insulation resistance	100MΩ (at 500VDC)		c. The products of 2Z or BZ adopt bridge connection method.		
Withstand voltage ⁵⁾	between contacts: 500VAC		d. The installation spacing between relay samples is 100mm.		
	between coil & contacts: 500VAC		e. It varies by connection conditions. Additionally, reliable performance under repeated power-on cannot be guaranteed. Verify based on actual operating conditions during use.		
Operate time	Max.:10ms (at nomi. vol.);Typ.:2ms		3) 23°C, 14VDC(100 cycles, resistive load);		
Release time ⁶⁾	Max.: 10ms;Typ.:1ms		4) Lower limit target for on-off operation at low load. This value varies by on-off frequency, environmental conditions and expected reliability level; verify with actual load during use.		
Ambient temperature	HFKF: -40°C to 85°C		5) 1min, leakage current less than 1mA.		
	HFKF-T: -40°C to 125°C		6) The value is measured when voltage drops suddenly from nominal voltage to 0 VDC and coil is not paralleled with suppression circuit.		
Vibration resistance	Functional ⁷⁾	10Hz to 300Hz 43m/s ²	7) When energized, opening time of NO contacts shall not exceed 1ms, when non-energized, opening time of NC contacts shall not exceed 1ms, meantime, NO contacts shall not be closed.		
	Destructive	10Hz to 500Hz 43m/s ² , 200h	8) When energized, opening time of NO contacts shall not exceed 10μs, when non-energized, opening time of NC contacts shall not exceed 10μs, meantime, NO contacts shall not be closed.		
			9) Since it is an environmental friendly product, please select lead-free solder when welding. The recommended soldering temperature and time is (260±3)°C, (5±0.5)s.		

CONTACT DATA³⁾

at 23°C

Load voltage	Load type ²⁾		Load current A		On/Off ratio		Electrical endurance OPS	Contact material	Load wiring diagram
			1C, 2C		On s	Off s			
			NO	NC					
14VDC	Resistive	Make	20	10	1	9	1 × 10 ⁵	AgSnO ₂	See diagram 1
		Break	20	10					
	Motor	Make ¹⁾	25	—	0.5	9.5	1 × 10 ⁵	AgSnO ₂	See diagram 2
		Break	25	—					
	Simulate motor operation	Make ¹⁾	25	—	0.02	9.5	2 × 10 ⁵	AgSnO ₂	
		Transient	15	—					
		Break	5	—	0.45				

Notes: 1) Corresponds to the peak inrush current on initial actuation (motor).
2) The load wiring diagrams are listed below:



HONGFA RELAY

ISO9001, IATF16949, ISO14001, ISO45001, IECQ QC 080000, ISO/IEC 27001 CERTIFIED

2025. Rev. 2.00

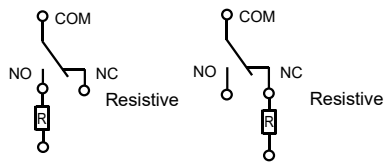


diagram 1

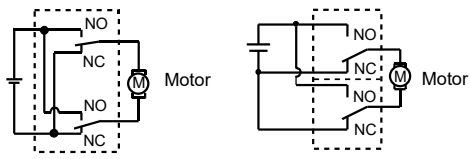


diagram 2

3) When the load requirement is different from content of the table above, please contact Hongfa for relay application support.

COIL DATA

Nominal voltage VDC	Pick-up voltage VDC max.			Drop-out voltage VDC min.			Coil resistance $\times(1\pm 10\%) \Omega$			Coil power consumption W
	23°C	85°C	125°C	23°C	85°C	125°C	23°C	85°C	125°C	23°C
12	6.5	8.1	9.1	0.8	1	1.13	160	199.7	225.3	0.9
12	7.7	9.6	10.9	0.8	1	1.13	220	274.6	309.8	0.655

ORDERING INFORMATION

		HFKF /		12	-1Z	S	P	T	(XXX)
Type		HFKF: Standard HFKF-T: Reflow soldering version or high heat-resistant version							
Coil voltage	12: 12VDC								
Contact arrangement	1Z: 1 Form C (Single version) BZ: 2 Form C (Twin(8 pins) version) ZZ: 2 Form C (Twin(10 pins) version)								
Construction¹⁾	S: Plastic sealed Nil: Flux proofed								
Coil power	P: 0.9W Nil: 0.655W								
Contact material	T: AgSnO ₂								
Special code²⁾	XXX: Customer special requirement				Nil: Standard				

Notes: 1) Contact us for suitable soldering conditions and product specifications if post-soldering cleaning or surface treatment is required after the relays are soldered onto the PCB.

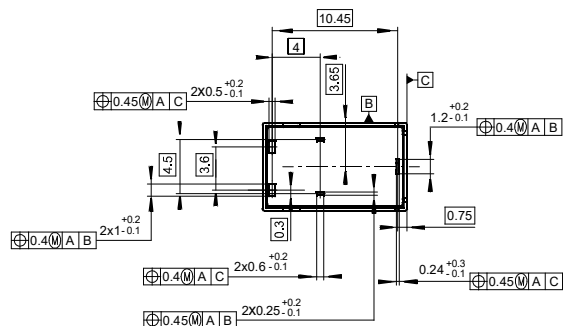
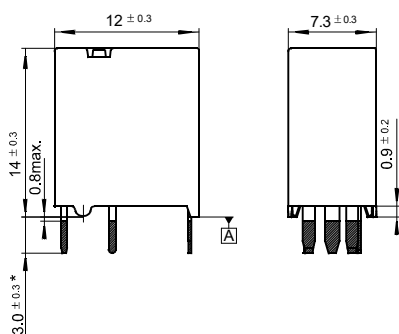
2) The customer special requirement express as special code after evaluating by Hongfa. e.g. (170) stands for flasher load. The performance parameters of products with characteristic numbers shall be subject to the specific specifications provided by Hongfa..

OUTLINE DIMENSIONS, WIRING DIAGRAM AND PC BOARD LAYOUT

Unit: mm

Outline Dimensions

1 Form C (Single relay)

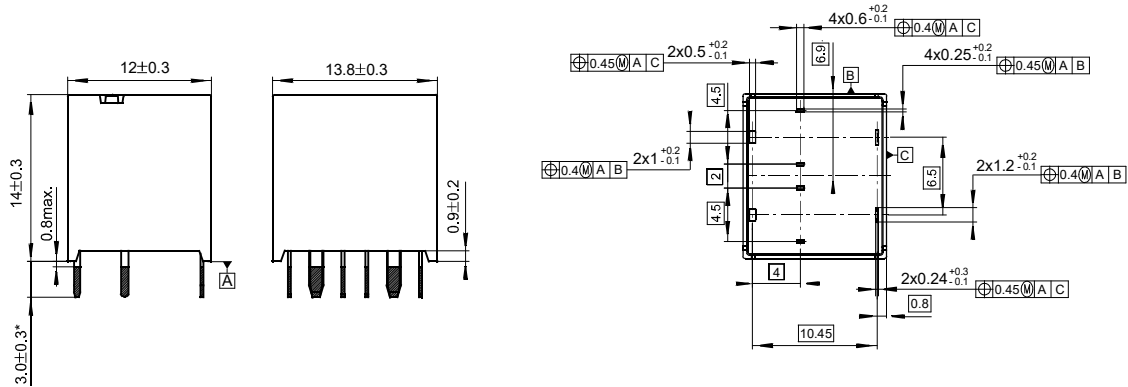


OUTLINE DIMENSIONS, WIRING DIAGRAM AND PC BOARD LAYOUT

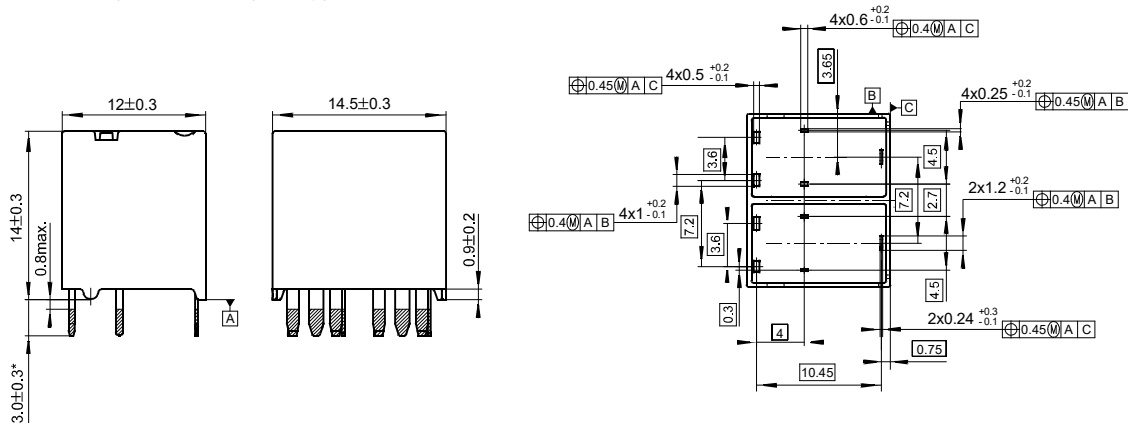
Unit: mm

Outline Dimensions

2 Form C (Twin(8 pins) relay)



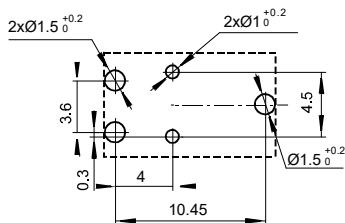
2 Form C (Twin(10 pins) relay)



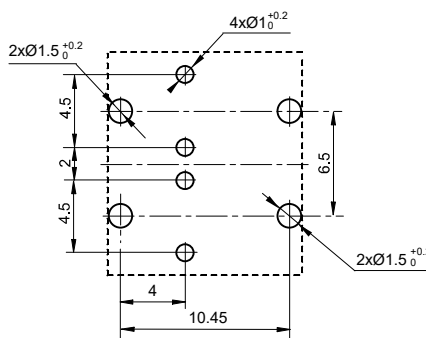
Remark: * The additional tin top is max. 1mm. Intervals between terminals is measured at A surface level.

PCB Layout (Bottom view)

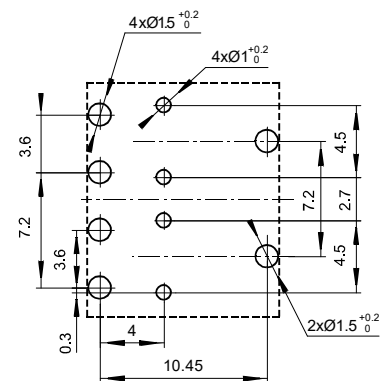
1 Form C (Single relay)



2 Form C (Twin(8 pins) relay)



2 Form C (Twin(10 pins) relay)



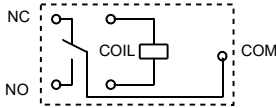
Undeclared tolerance: ± 0.1 .

OUTLINE DIMENSIONS, WIRING DIAGRAM AND PC BOARD LAYOUT

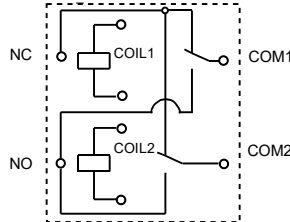
Unit: mm

Wiring Diagram (Bottom view)

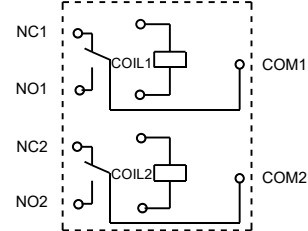
1 Form C (Single relay)



2 Form C (Twin(8 pins)) relay



2 Form C (Twin(10 pins)) relay



CHARACTERISTIC CURVES

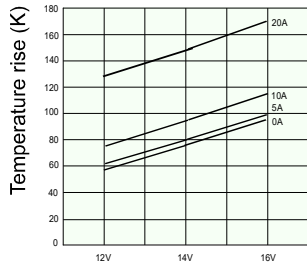
(1) Coil temperature rise (23°C)

Experiment: HFKF/12-BZSPT

Amount: three

Carrying current: 0A, 5A, 10A, 20A

Ambient temp.: 23°C



Coil voltage (VDC)

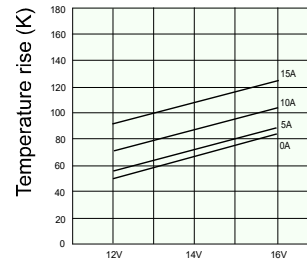
(2) Coil temperature rise (85°C)

Experiment: HFKF/12-BZSPT

Amount: three

Carrying current: 0A, 5A, 10A, 15A

Ambient temp.: 85°C



Coil voltage (VDC)

Remark: The coil temperature rise test requires the relay to be installed on the PCB. The PCB is double-layered. The thickness of the copper foil is 4 oz (140 μm), the width of each copper foil is $3.76 \times (1 \pm 5\%)$ mm, the length of the copper foil is $50\text{mm} \pm 1\text{mm}$, and the Tg value of the PCB board is 150°C. The installation spacing between relay samples is 100mm.

Disclaimer

The specification is for reference only. See to "Terminology and Guidelines" for more information. Specifications subject to change without notice. In case there is specific criterion (such as mission profile, technical specification, PPAP etc.) checked and agreed by and between customer and Hongfa, this specific criterion should be taken as standard regarding any requirement on Hongfa product.

We could not evaluate all the performance and all the parameters for every possible application. Thus the user should be in a right position to choose the suitable product for their own application. If there is any query, please contact Hongfa for the technical service. However, it is the user's responsibility to determine which product should be used only.

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